



# FEMTOCLOCKS™ CRYSTAL-TO-HSTL FREQUENCY SYNTHESIZER

## ICS8421002I

### GENERAL DESCRIPTION



The ICS8421002I is a 2 output HSTL Synthesizer optimized to generate Fibre Channel reference clock frequencies and is a member of the HiPerClocks™ family of high performance clock solutions from IDT. Using a 26.5625MHz 18pF parallel resonant crystal, the following frequencies can be generated based on the 2 frequency select pins (F\_SEL[1:0]): 212.5MHz, 187.5MHz, 159.375MHz, 106.25MHz and 53.125MHz. The ICS8421002I uses IDT's 3<sup>rd</sup> generation low phase noise VCO technology and can achieve 1ps or lower typical rms phase jitter, easily meeting Fibre Channel jitter requirements. The ICS8421002I is packaged in a small 20-pin TSSOP package.

### FEATURES

- Two HSTL outputs (VOHmax = 1.5V)
- Selectable crystal oscillator interface or LVCMOS/LVTTL single-ended input
- Supports the following output frequencies: 212.5MHz, 187.5MHz, 159.375MHz, 106.25MHz, 53.125MHz
- VCO range: 560MHz - 680MHz
- RMS phase jitter @ 212.5MHz, using a 26.5625MHz crystal (637kHz - 10MHz): 0.59ps (typical)
- Power supply modes:  
Core/Output  
3.3V/1.8V  
2.5V/1.8V
- -40°C to 85°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

FREQUENCY SELECT FUNCTION TABLE

Input Frequency (MHz)	Inputs					Output Frequency (MHz)
	F_SEL1	F_SEL0	M Divider Value	N Divider Value	M/N Divider Value	
26.5625	0	0	24	3	8	212.5
26.5625	0	1	24	4	6	159.375
26.5625	1	0	24	6	4	106.25
26.5625	1	1	24	12	2	53.125
23.4375	0	0	24	3	8	187.5

### PIN ASSIGNMENT

nc	1	20	VDD0
VDD0	2	19	Q1
Q0	3	18	nQ1
nQ0	4	17	GND
MR	5	16	VDD
nPLL_SEL	6	15	nXTAL_SEL
nc	7	14	REF_CLK
VDDA	8	13	XTAL_IN
F_SEL0	9	12	XTAL_OUT
VDD	10	11	F_SEL1

### ICS8421002I

#### 20-Lead TSSOP

6.5mm x 4.4mm x 0.92mm package body

**G Package**  
Top View

### BLOCK DIAGRAM

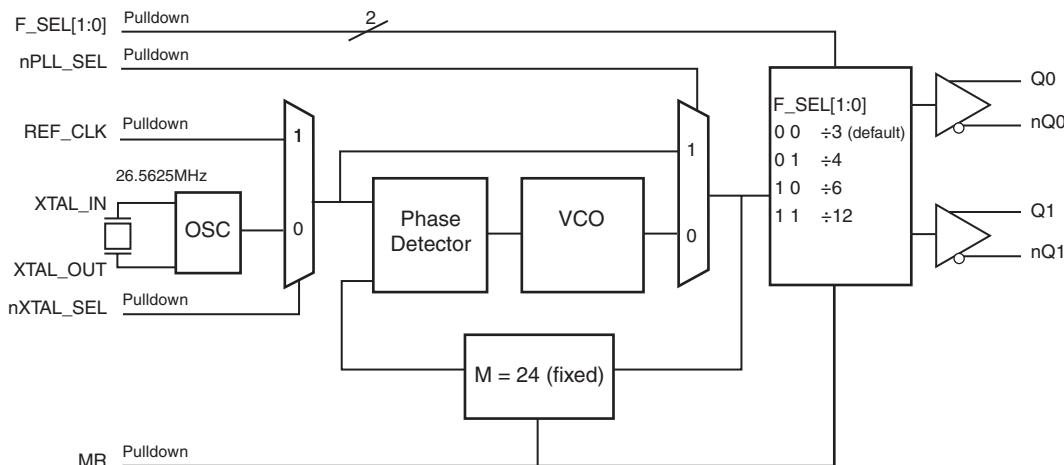


TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 7	nc	Unused		No connect.
2, 20	V <sub>DDO</sub>	Power		Output supply pins.
3, 4	Q0, nQ0	Output		Differential output pair. HSTL interface levels.
5	MR	Input	Pulldown	Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the true outputs Qx to go low and the inverted outputs nQx to go high. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS/LVTTL interface levels.
6	nPLL_SEL	Input	Pulldown	Selects between the PLL and REF_CLK as input to the dividers. When LOW, selects PLL (PLL Enable). When HIGH, deselects the reference clock (PLL Bypass). LVCMOS/LVTTL interface levels.
8	V <sub>DDA</sub>	Power		Analog supply pin.
9, 11	F_SEL0, F_SEL1	Input	Pulldown	Frequency select pins. LVCMOS/LVTTL interface levels.
10, 16	V <sub>DD</sub>	Power		Core supply pin.
12, 13	XTAL_OUT, XTAL_IN	Input		Parallel resonant crystal interface. XTAL_OUT is the output, XTAL_IN is the input.
14	REF_CLK	Input	Pulldown	LVCMOS/LVTTL reference clock input.
15	nXTAL_SEL	Input	Pulldown	Selects between crystal or REF_CLK inputs as the the PLL Reference source. Selects XTAL inputs when LOW. Selects REF_CLK when HIGH. LVCMOS/LVTTL interface levels.
17	GND	Power		Power supply ground.
18, 19	nQ1, Q1	Output		Differential output pair. HSTL interface levels.

NOTE: *Pulldown* refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ

## ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$	-0.5V to $V_{DD} + 0.5V$
Outputs, $I_O$	
Continuous Current	50mA
Surge Current	100mA
Package Thermal Impedance, $\theta_{JA}$	73.2°C/W (0 lfpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 3A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = 3.3V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{DDA}$	Analog Supply Voltage		3.135	3.3	3.465	V
$V_{DDO}$	Output Supply Voltage		1.6	1.8	2.0	V
$I_{DD}$	Power Supply Current				110	mA
$I_{DDA}$	Analog Supply Current				12	mA
$I_{DDO}$	Output Supply Current	No Load		0		mA

TABLE 3B. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = 2.5V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		2.375	2.5	2.625	V
$V_{DDA}$	Analog Supply Voltage		2.375	2.5	2.625	V
$V_{DDO}$	Output Supply Voltage		1.6	1.8	2.0	V
$I_{DD}$	Power Supply Current				96	mA
$I_{DDA}$	Analog Supply Current				12	mA
$I_{DDO}$	Output Supply Current	No Load		0		mA

TABLE 3C. LVCMOS / LVTTTL DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = 3.3V \pm 5\%$  OR  $2.5V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage	$V_{DD} = 3.3V$	2		$V_{DD} + 0.3$	V
		$V_{DD} = 2.5V$	1.7		$V_{DD} + 0.3$	V
$V_{IL}$	Input Low Voltage	$V_{DD} = 3.3V$	-0.3		0.8	V
		$V_{DD} = 2.5V$	-0.3		0.7	V
$I_{IH}$	Input High Current	REF_CLK, MR, F_SEL0, F_SEL1, nPLL_SEL, nXTAL_SEL $V_{DD} = V_{IN} = 3.465V$ or 2.5V			150	$\mu\text{A}$
$I_{IL}$	Input Low Current	REF_CLK, MR, F_SEL0, F_SEL1, nPLL_SEL, nXTAL_SEL $V_{DD} = 3.465V$ or 2.5V, $V_{IN} = 0V$	-150			$\mu\text{A}$

**TABLE 3D. HSTL DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = 3.3V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OH}$	Output High Voltage; NOTE 1		1.0		1.5	V
$V_{OL}$	Output Low Voltage; NOTE 1		0		0.5	V
$V_{OX}$	Output Crossover Voltage; NOTE 2		40		60	%
$V_{SWING}$	Peak-to-Peak Output Voltage Swing		0.6		1.3	V

NOTE 1: Outputs terminated with  $50\Omega$  to ground.

NOTE 2: Defined with respect to output voltage swing at a given condition.

**TABLE 3E. HSTL DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = 2.5V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OH}$	Output High Voltage; NOTE 1		0.8		1.5	V
$V_{OL}$	Output Low Voltage; NOTE 1		0		0.6	V
$V_{OX}$	Output Crossover Voltage; NOTE 2		40		60	%
$V_{SWING}$	Peak-to-Peak Output Voltage Swing		0.5		1.5	V

NOTE 1: Outputs terminated with  $50\Omega$  to ground.

NOTE 2: Defined with respect to output voltage swing at a given condition.

**TABLE 4. CRYSTAL CHARACTERISTICS**

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation		Fundamental			
Frequency		23.33	26.5625	28.33	MHz
Equivalent Series Resistance (ESR)				50	$\Omega$
Shunt Capacitance				7	pF
Drive Level				1	mW

NOTE: Characterized using an 18pF parallel resonant crystal.

TABLE 5A. AC CHARACTERISTICS,  $V_{DD} = V_{DDA} = 3.3V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{OUT}$	Output Frequency	F_SEL[1:0] = 00	186.67		226.66	MHz
		F_SEL[1:0] = 01	140		170	MHz
		F_SEL[1:0] = 10	93.33		113.33	MHz
		F_SEL[1:0] = 11	46.67		56.66	MHz
$t_{sk(o)}$	Output Skew; NOTE 1, 3			20	ps	
$f_{jit}(\emptyset)$	RMS Phase Jitter (Random); NOTE 2	212.5MHz, (637kHz - 10MHz)		0.59		ps
		187.5MHz, (1.875MHz - 20MHz)		0.51		ps
		159.375MHz, (637kHz - 10MHz)		0.56		ps
		106.25MHz, (637kHz - 10MHz)		0.69		ps
		53.125MHz, (637kHz - 10MHz)		0.66		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%	175		875	ps
odc	Output Duty Cycle	N Divider = 4, 6, 12	48		52	%
		N Divider = 3	44		56	%

NOTE 1: Defined as skew between outputs at the same supply voltages and with equal load conditions.

Measured at  $V_{DDO}/2$ .

NOTE 2: Please refer to the Phase Noise Plot.

NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.

TABLE 5B. AC CHARACTERISTICS,  $V_{DD} = V_{DDA} = 2.5V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{OUT}$	Output Frequency	F_SEL[1:0] = 00	186.67		226.66	MHz
		F_SEL[1:0] = 01	140		170	MHz
		F_SEL[1:0] = 10	93.33		113.33	MHz
		F_SEL[1:0] = 11	46.67		56.66	MHz
$t_{sk(o)}$	Output Skew; NOTE 1, 3			20	ps	
$f_{jit}(\emptyset)$	RMS Phase Jitter (Random); NOTE 2	212.5MHz, (637kHz - 10MHz)		0.60		ps
		187.5MHz, (1.875MHz - 20MHz)		0.70		ps
		159.375MHz, (637kHz - 10MHz)		0.64		ps
		106.25MHz, (637kHz - 10MHz)		0.70		ps
		53.125MHz, (637kHz - 10MHz)		0.68		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%	200		700	ps
odc	Output Duty Cycle	N Divider = 4, 6, 12	48		52	%
		N Divider = 3	44		56	%

NOTE 1: Defined as skew between outputs at the same supply voltages and with equal load conditions.

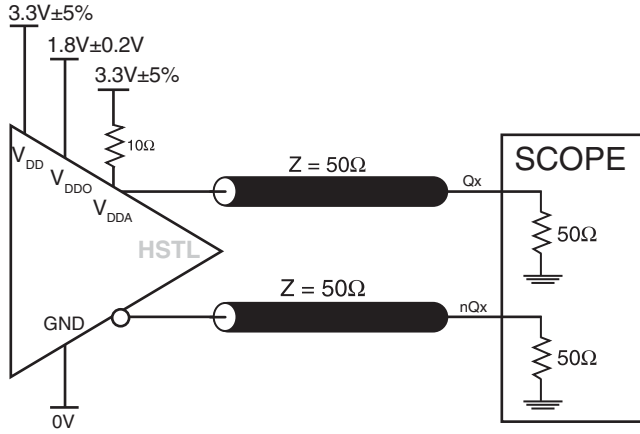
Measured at  $V_{DDO}/2$ .

NOTE 2: Please refer to the Phase Noise Plot.

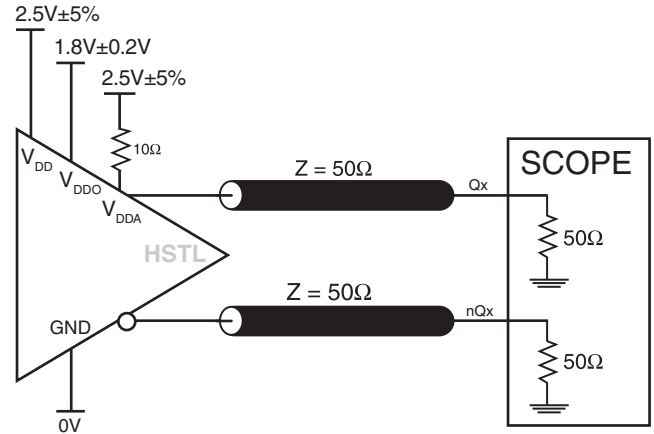
NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.



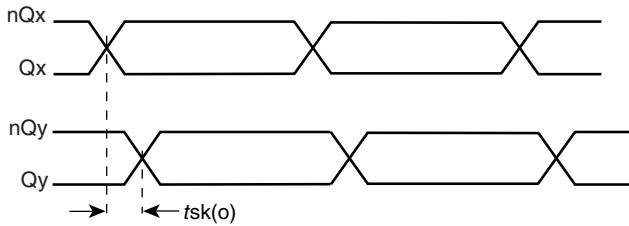
## PARAMETER MEASUREMENT INFORMATION



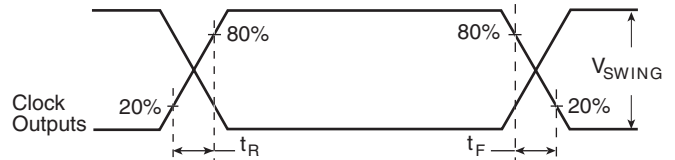
HSTL 3.3V/1.8V OUTPUT LOAD AC TEST CIRCUIT



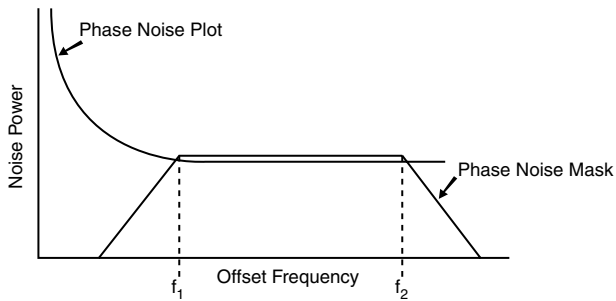
HSTL 2.5V/1.8V OUTPUT LOAD AC TEST CIRCUIT



OUTPUT SKEW

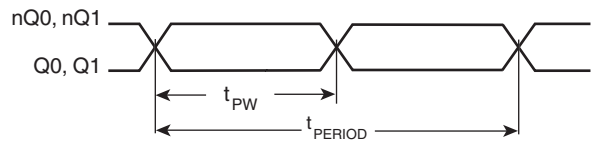


OUTPUT RISE/FALL TIME



$$\text{RMS Jitter} = \sqrt{\text{Area Under the Masked Phase Noise Plot}}$$

RMS PHASE JITTER



$$\text{odc} = \frac{t_{PW}}{t_{PERIOD}} \times 100\%$$

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

## APPLICATION INFORMATION

### POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS8421002I provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL.  $V_{DD}$ ,  $V_{DDA}$ , and  $V_{DDO}$  should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. *Figure 1* illustrates how a  $10\Omega$  resistor along with a  $10\mu\text{F}$  and a  $.01\mu\text{F}$  bypass capacitor should be connected to each  $V_{DDA}$ .

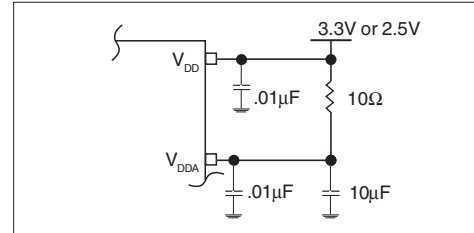


FIGURE 1. POWER SUPPLY FILTERING

### CRYSTAL INPUT INTERFACE

The ICS8421002I has been characterized with 18pF parallel resonant crystals. The capacitor values shown in *Figure 2* below

were determined using a 26.5625MHz 18pF parallel resonant crystal and were chosen to minimize the ppm error.

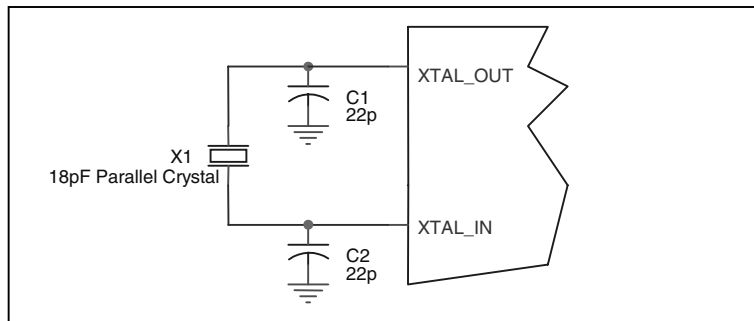


Figure 2. CRYSTAL INPUT INTERFACE

### RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

#### INPUTS:

##### CRYSTAL INPUT:

For applications not requiring the use of the crystal oscillator input, both XTAL\_IN and XTAL\_OUT can be left floating. Though not required, but for additional protection, a  $1\text{k}\Omega$  resistor can be tied from XTAL\_IN to ground.

##### REF\_CLK INPUT:

For applications not requiring the use of the reference clock, it can be left floating. Though not required, but for additional protection, a  $1\text{k}\Omega$  resistor can be tied from the REF\_CLK to ground.

##### LVC MOS CONTROL PINS:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A  $1\text{k}\Omega$  resistor can be used.

#### OUTPUTS:

##### HSTL OUTPUT

All unused HSTL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.



## POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS8421002I. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the ICS8421002I is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{DD} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

**NOTE:** Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> =  $V_{DD,MAX} * I_{DD,MAX} = 3.465V * 122mA = 422.7mW$
- Power (outputs)<sub>MAX</sub> = **32.8mW/Loaded Output pair**  
If all outputs are loaded, the total power is  $2 * 32.8mW = 65.6mW$

**Total Power**<sub>MAX</sub> (3.465V, with all outputs switching) =  $422.7mW + 65.6mW = 488.3mW$

### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 66.6°C/W per Table 6 below.

Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:  
 $85°C + 0.488W * 66.6°C/W = 117.5°C$ . This is below the limit of 125°C.

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

**TABLE 6. THERMAL RESISTANCE  $\theta_{JA}$  FOR 20-PIN TSSOP, FORCED CONVECTION**

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

HSTL output driver circuit and termination are shown in *Figure 3*.

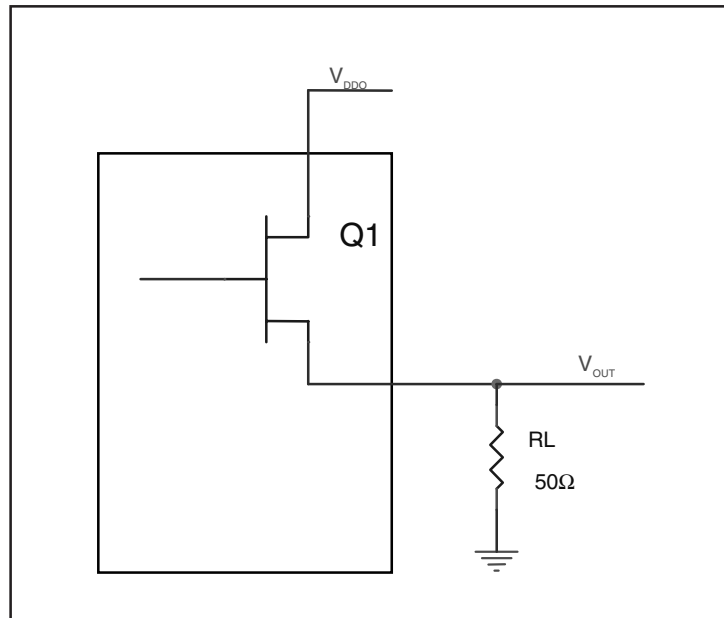


FIGURE 3. HSTL DRIVER CIRCUIT AND TERMINATION

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load.

Pd\_H is power dissipation when the output drives high.

Pd\_L is the power dissipation when the output drives low.

$$Pd_H = (V_{OH\_MAX} / R_L) * (V_{DD\_MAX} - V_{OH\_MAX})$$

$$Pd_L = (V_{OL\_MAX} / R_L) * (V_{DD\_MAX} - V_{OL\_MAX})$$

$$Pd_H = (1V/50\Omega) * (2V - 1V) = \mathbf{20mW}$$

$$Pd_L = (0.4V/50\Omega) * (2V - 0.4V) = \mathbf{12.8mW}$$

$$\text{Total Power Dissipation per output pair} = Pd_H + Pd_L = \mathbf{32.8mW}$$

## RELIABILITY INFORMATION

TABLE 7.  $\theta_{JA}$  vs. AIR FLOW TABLE FOR 20 LEAD TSSOP

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### TRANSISTOR COUNT

The transistor count for ICS8421002I is: 2951

PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

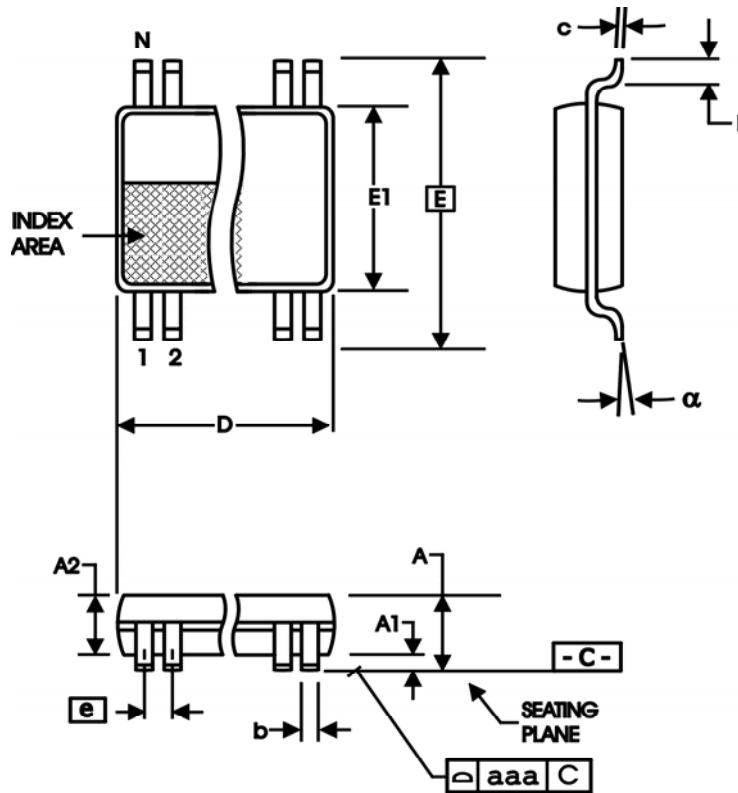


TABLE 8. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MIN	MAX
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153

**TABLE 9. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS8421002AGI	ICS8421002AI	20 Lead TSSOP	tube	-40°C to 85°C
ICS8421002AGIT	ICS8421002AI	20 Lead TSSOP	2500 tape & reel	-40°C to 85°C
ICS8421002AGILF	ICS421002AIL	20 Lead "Lead-Free" TSSOP	tube	-40°C to 85°C
ICS8421002AGILFT	ICS421002AIL	20 Lead "Lead-Free" TSSOP	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free Configuration and are RoHS compliant.

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## REVISION HISTORY SHEET

Rev	Table	Page	Description of Change	Date
B	3A, 3B	3	Power Supply Tables - corrected $V_{DDO}$ min/max.	8/7/06

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---

**Corporate Headquarters**

Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road  
San Jose, CA 95138  
United States  
800 345 7015  
+408 284 8200 (outside U.S.)

**Asia Pacific and Japan**

Integrated Device Technology  
Singapore (1997) Pte. Ltd.  
Reg. No. 199707558G  
435 Orchard Road  
#20-03 Wisma Atria  
Singapore 238877  
+65 6 887 5505

**Europe**

IDT Europe, Limited  
321 Kingston Road  
Leatherhead, Surrey  
KT22 7TU  
England  
+44 (0) 1372 363 339  
Fax: +44 (0) 1372 378851

